Material Composition Declaration

© Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.

This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.

Adobe Reader version 7.0.5 is required to complete this declaration.

1752-2 1.1	IPC Web Site for Information on IPC-1752 Standard http://www.ipc.org/IPC-175x	**Form Type *** Distribute	**Declaration Class *** Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg Informat

Supplier Information

Company Name *	Company Unique ID	Unique ID Authority	**Response Date ***	Response Document ID	
CHiL Semiconductor			**2010-10-25**		
Contact Name *	Title - Contact	**Phone - Contact ***	**Email - Contact ***		
Manu Jain		**978-640-0011**	**quality@chilsemi.com**		
Authorized Representative *	Title - Representative	**Phone - Representative ***	**Email - Representative** *	Supplier Comments or URL for Additional Information	
Manu Jain		**978-640-0011**	**quality@chilsemi.com**		

Requester Item Number	Mfr Item Number	Mfr Item Name	Effective Date	Version	Manufacturing Site	**Weight ***	UOM	Unit Type
	CHL8113	CHL8113	2010-10-25			89.16	mg	Each

Alternate Recommendation				Alternate Item Comments	

Manufacturing Process Information

Terminal Plating / Grid Array Material	Terminal Base Alloy	J-STD-020 MSL Rating	Peak Process Body Temperature	Max Time at Peak Temperature	Number of Reflow Cycles
Silver (Ag)	**CU Alloy**	**3**	**264.5** C	**25** seconds	**1**

Comments

Does not contain PFOS

*** Required Field**

CAS Registry Number(R) is a Registered Trademark of the American Chemical Society

Form enabled by Adobe

Save the fields in this form to a file [Export Data] Import fields from a file into this form [Import Data] Locked

RoHS Material Composition Declaration

Declaration Type * **Custom**

RoHS Directive 2002/95/EC	**RoHS Definition:** Quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium, Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE) and quantity limit of 0.01% by mass (100 PPM) of homogeneous material for Cadmium

Subject to the limitations below, CHiL Semiconductor Corporation certifies the following information as of the document date.

1. CHiL products designated "ROHS Compliant" comply with the European Unions Directive on the Restriction of the Use of Hazardous Substances 2002/95/EC ("RoHS").
2. CHiL products do not contain and are not manufactured with ozone depleting compounds.
3. CHiL products do not contain substances identified by the European Chemical Agency ("ECHA") as substances of very high concern ("SVHC") per REACH Regulation (EC) No 1907/2006. CHiL also complies with use restrictions as stipulated in Annex XVII of REACH.
4. CHiL's list of banned and reportable substances and management system is based on the current version of the Joint Industrial Guide, JIG-101.

CHiL has taken commercially reasonable steps to provide representative and accurate information but may not have independently verified information provided or conducted chemical analysis of incoming materials. Equivalent compliant materials may have been substituted for those stated herein. Material concentrations are the maximum expected concentration of the substance in the device and may not represent the actual concentration. CHiL and its suppliers consider certain limited information to be confidential and thus CAS numbers and other limited information may not be available for release.

CHiL ACCEPTS NO DUTY TO NOTIFY USERS OF THIS DECLARATION OF UPDATES OR CHANGES TO THIS DECLARATION

RoHS Declaration *	1 - Item(s) does not contain RoHS restricted substances per the definition above	**Supplier Acceptance ***	**Accepted**

Exemptions: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.

Declaration Signature

Instructions: Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.

Supplier Digital Signature	 Manu Jain 2010.12.16 17:10:04 -05'00'	

*** Required Field**

CAS Registry Number(R) is a Registered Trademark of the American Chemical Society

Form enabled by Adobe

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Line Functions: +I Inserts a New Item /SubItem +M Inserts a new Material +C Inserts a new Substance Category +S Inserts a new Substance - Deletes the element line

	Item/SubItem Name		Homogeneous Material	Weight	Unit of Measure		Level	Substance Category		Substance	CAS	Exempt	Weight	Unit of Measure	Tolerance -	Tolerance +	PPM
			Mold Compound	33.5	mg		Supplier			Silica Fused	60676-86-0						375,72
										Silica Fused	60676-86-0		30.3845	mg			340,78
										Carbon Black			0.1005	mg			1,127
										Proprietary Epoxy Resi			1.005	mg			11,272
										Proprietary Epoxy Resi			0.5025	mg			5,636
										Proprietary Phenol Res			1.005	mg			11,272
										Proprietary Metal Hydro			0.5025	mg			5,636
			Leadframe	38.44	mg		Supplier							mg			431,07
										Copper (Cu)	7440-50-8		37.09027	mg			415,99
										Plated Silver	7440-22-4		0.96089	mg			10,777
										Proprietary Others			0.38436	mg			4,311
			Die	4.58	mg		Supplier							mg			51,399
			Die Attach	0.59	mg		Supplier							mg			6,605
										Silver	7440-22-4		0.43876	mg			4,921
										Proprietary Acrylic Res			0.05006	mg			561
										Proprietary Polybutadie			0.02356	mg			264
										Proprietary Butadiene c			0.01178	mg			132
										Proprietary Epoxy resin			0.01472	mg			165
										Proprietary Acrylate			0.03239	mg			363
										Proprietary Peroxide			0.00589	mg			66
										Proprietary Additive			0.01178	mg			132
			Wire	0.24298	mg		Supplier							mg			2,725
										Cu	7440-50-8		0.23836	mg			2,673

*** Required Field**

CAS Registry Number(R) is a Registered Trademark of the American Chemical Society

Form enabled by Adobe
